1st Announcement and Call for Papers

The 29th International Symposium on Power Semiconductor Devices and ICs

ISPSD 2017
May 28 -June 1, 2017
SAPPORO, Japan

Conference site: Royton Sapporo

Main categories of interest include:

- **High Voltage Power Devices**: Medium and high voltage Si bipolar devices such as IGBT, thyristor, pn diode, etc.
- **Low Voltage Power Devices**: Low and medium voltage Si unipolar devices such as power MOSFETs, SJ type devices, etc.
- **New Material Power Devices**: Power devices based on compound or new materials such as SiC, GaN, diamond
- **Power ICs**: Integrated power devices and circuitry on a single or multi chip(s) architecture
- **Module and Package Technologies**: Integrated power modules and packaging technologies (functionality, power density, isolation, reliability, device cooling, temperature endurance, manufacturing, materials, etc.)

**< Important date>**
Abstract Submission Deadline : November 15, 2016

**< Direct Flights to New Chitose Airport>**
Seoul (Incheon) , Busan , Shanghai, Taipei , Hong Kong, Bangkok

**< Connecting Flights>**

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<th>City</th>
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**< Airport to Downtown Sapporo >**
Airport express train: 37 min. to downtown, available every 10-15 minutes

General Chair: Dr. Mutsuhiro Mori, Hitachi, Ltd.
Vice General Chair: Dr. Kimimori Hamada, Toyota Motor Corporation
Technical Program Chair: Prof. Ichiro Omura, Kyushu Institute of Technology

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